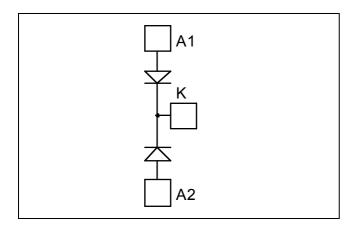


Dual Common Cathode diodes Power Module

$$V_{RRM} = 1000V$$

 $I_C = 400A$ @ $Tc = 70$ °C



Application

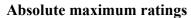
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

Features

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
 - Symmetrical design
 - M5 power connectors
- High level of integration



- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant



Symbol	Parameter				Max ratings	Unit	
V_R	Maximum DC reverse Voltage			1000	V		
V_{RRM}	Maximum Peak Repetitive Revers	e Voltage			1000	V	
$I_{F(AV)}$	Maximum Average Forward	Duty avala = 6	500/	$T_C = 25^{\circ}C$	500		
	Current	Duty cycle = 5	00%	$T_{\rm C} = 25^{\circ}{\rm C}$ $T_{\rm C} = 70^{\circ}{\rm C}$	400	Α	
I _{F(RMS)}	RMS Forward Current	Duty cycle = 50%		$T_C = 45$ °C	500	А	
I_{FSM}	Non-Repetitive Forward Surge Cu	rrent 8.3ms		$T_C = 45$ °C	3000		

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

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All ratings @ $T_j = 25$ °C unless otherwise specified

Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
V_{F}	Diode Forward Voltage	$I_F = 400A$			2.1	2.7	
		$I_F = 600A$			2.3		V
		$I_F = 400A$	$T_{j} = 125^{\circ}C$		1.7		
I_{RM}	Maximum Davarga Laglaga Cumant	$V_R = 1000V$ $T_i = 25^{\circ}C$ $T_j = 125^{\circ}C$	$T_i = 25^{\circ}C$			250	^
	Maximum Reverse Leakage Current		$T_j = 125$ °C			1000	μΑ
C_{T}	Junction Capacitance	$V_R = 1000V$			480		pF

Dynamic Characteristics

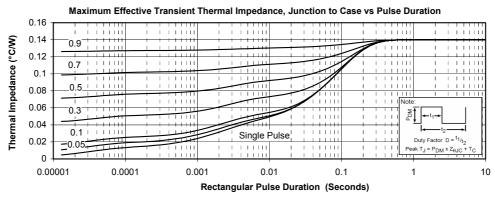
Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
t_{rr}	Reverse Recovery Time	$I_F=1A, V_R=30V$ $di/dt = 400A/\mu s$	$T_j = 25^{\circ}C$		45		ns
t _{rr}	Reverse Recovery Time		$T_j = 25$ °C		290		- ns
			$T_j = 125$ °C		340		
Qrr	Reverse Recovery Charge	$I_F = 400A$ $V_R = 667V$ $di/dt = 800A/\mu s$	$T_j = 25$ °C		2.7		μС
Vп	Reverse Recovery Charge		$T_j = 125$ °C		14.6		
Ţ	Reverse Recovery Current		$T_j = 25$ °C		24		Α
I_{RRM}	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		72		Λ
t_{rr}	Reverse Recovery Time	$I_F = 400A$ $V_R = 667V$ $di/dt = 4000A/\mu s$			160		ns
Qrr	Reverse Recovery Charge		$T_j = 125$ °C		28.4		μС
I_{RRM}	Reverse Recovery Current				280		Α

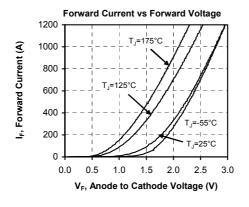
Thermal and package characteristics

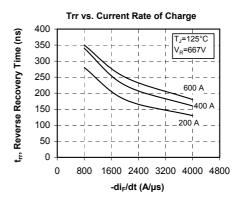
Symbol	Characteristic			Min	Тур	Max	Unit		
R_{thJC}	Junction to Case					0.14	°C/W		
V_{ISOL}	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V		
T_{J}	Operating junction temperature range			-40		175			
T_{STG}	Storage Temperature Range			-40		125	°C		
T_{C}	Operating Case Temperature					100	1		
Torque	Mounting torque	To heatsink	M6	3		5	N.m		
	Woulding torque	For terminals	M5	2		3.5	11.111		
Wt	Package Weight					300	g		

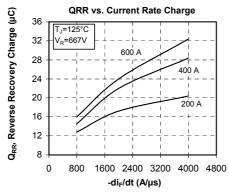


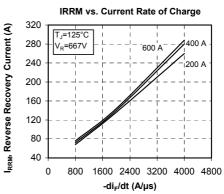
Typical Performance Curve

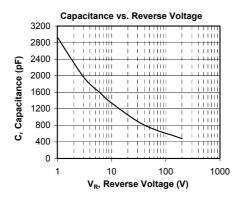


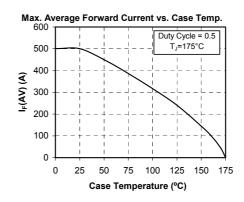








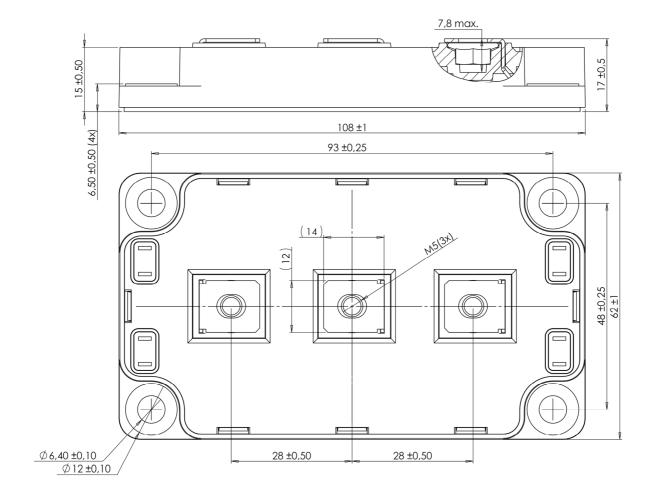




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SP6 Package outline (dimensions in mm)





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